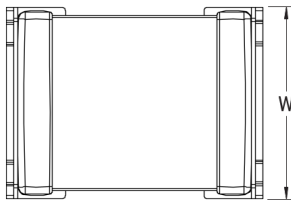
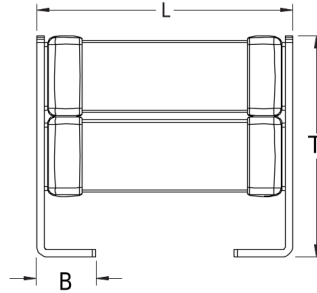


TOP VIEW
Single or Double Chip Stack



SIDE VIEW
Double Chip Stack



Click [here](#) for the 3D model.

Dimensions

L	6mm +/-0.5mm
W	5mm +/-0.5mm
T	5mm +/-0.50mm
B	1.6mm +/-0.3mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	800

General Information

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Double Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	800 mg
Chip Size	2220-2
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	22 uF
Measurement Condition	120 Hz 0.5Vrms
Capacitance Tolerance	20%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 120Hz 0.5Vrms
Dissipation Factor	2.5% 120 Hz 0.5Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	22.7 MOhms

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